

IN THE DRAWINGS

The attached sheet of drawings includes changes to Figs. 1-1 and 1-2. This sheet, which includes Figs. 1-1 and 1-2, replaces the original sheet including Figs. 1-1 and 1-2.

Attachment: Replacement Sheet

REMARKS

Favorable reconsideration of this application, as presently amended and in light of the following discussion, is respectfully requested.

Claims 1-18 are currently pending, with Claims 5-18 withdrawn from consideration. Claims 1 and 4 have been amended by the present amendment. No new matter has been added.¹

In the outstanding Office Action, Figures 1-1 and 1-2 were objected to; Claims 1-4 were rejected under 35 U.S.C. § 112, second paragraph, as indefinite; Claim 1 was rejected under 35 U.S.C. § 102(b) as anticipated by Takahashi et al. (U.S. Patent No. 5,661,343); Claim 2 was rejected under 35 U.S.C. § 103(a) as unpatentable over Takahashi in view of Isshiki et al. (U.S. Patent No. 6,235,862); and Claims 3-4 were rejected under 35 U.S.C. § 103(a) as unpatentable over Takahashi.

First, Applicants wish to thank Examiner Li and Primary Examiner Nadav for the courtesy of a personal interview granted to Applicants' representatives on July 22, 2008, during which the outstanding issues in the present application were discussed. During the interview, amendments which may overcome the outstanding rejections were discussed. The present amendment includes suggestions discussed during the interview.

Claims 1 and 4 have been amended to address the clarity issues raised in the outstanding Office Action. Applicants respectfully submit that amended Claims 1 and 4 are definite, and request that the rejections of Claims 1-4 under 35 U.S.C. § 112, second paragraph, be withdrawn.

Amended Claim 1 recites a metal base circuit board to be used for a hybrid integrated circuit. The metal base circuit board includes a plurality of circuit pads provided on a metal plate. The metal base circuit board also includes an insulating layer in between the plurality

¹ Amended Claims 1 and 4 are supported by Figures 1-3 and 1-4.

of the circuit pads and the metal plate, a power semiconductor mounted on one circuit pad of the plurality of the circuit pads, and a control semiconductor configured to control the power semiconductor, provided on another circuit pad of the plurality of the circuit pads. Further, the metal base circuit board includes a low capacitance portion *embedded in the metal plate under the insulating layer and under the another circuit pad of the portion of the plurality of the circuit pads on which the control semiconductor is mounted*. Claim 4 has been amended to recite *another insulating layer between the insulating layer and the metal plate, and the low capacitance portion is embedded in the metal plate and in the another insulating layer and is below the insulating layer*.

Turning now to the applied reference, Takahashi describes a power hybrid integrated circuit apparatus, which lacks any low capacitance portion **embedded in the metal plate and below the insulating layer**. Specifically, Takahashi at Figure 10 illustrates a power hybrid integrated circuit apparatus with a metal substrate 1, and **nothing embedded therein**. Accordingly, Applicants respectfully submit that amended Claims 1 and 4 (and all associated dependent claims) patentably define over Takahashi.

Turning now to the secondary reference, Isshiki describes an adhesive silicone sheet, that fails to cure the deficiency of Takahashi discussed above. Accordingly, Applicants respectfully submit that Claims 1 and 4 (and all associated dependent claims) patentably define over any proper combination of Takahashi and Isshiki.

Consequently, in light of the above discussion and in view of the present amendment, the present application is believed to be in condition for allowance. An early and favorable action to that effect is respectfully requested.

Respectfully submitted,

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